



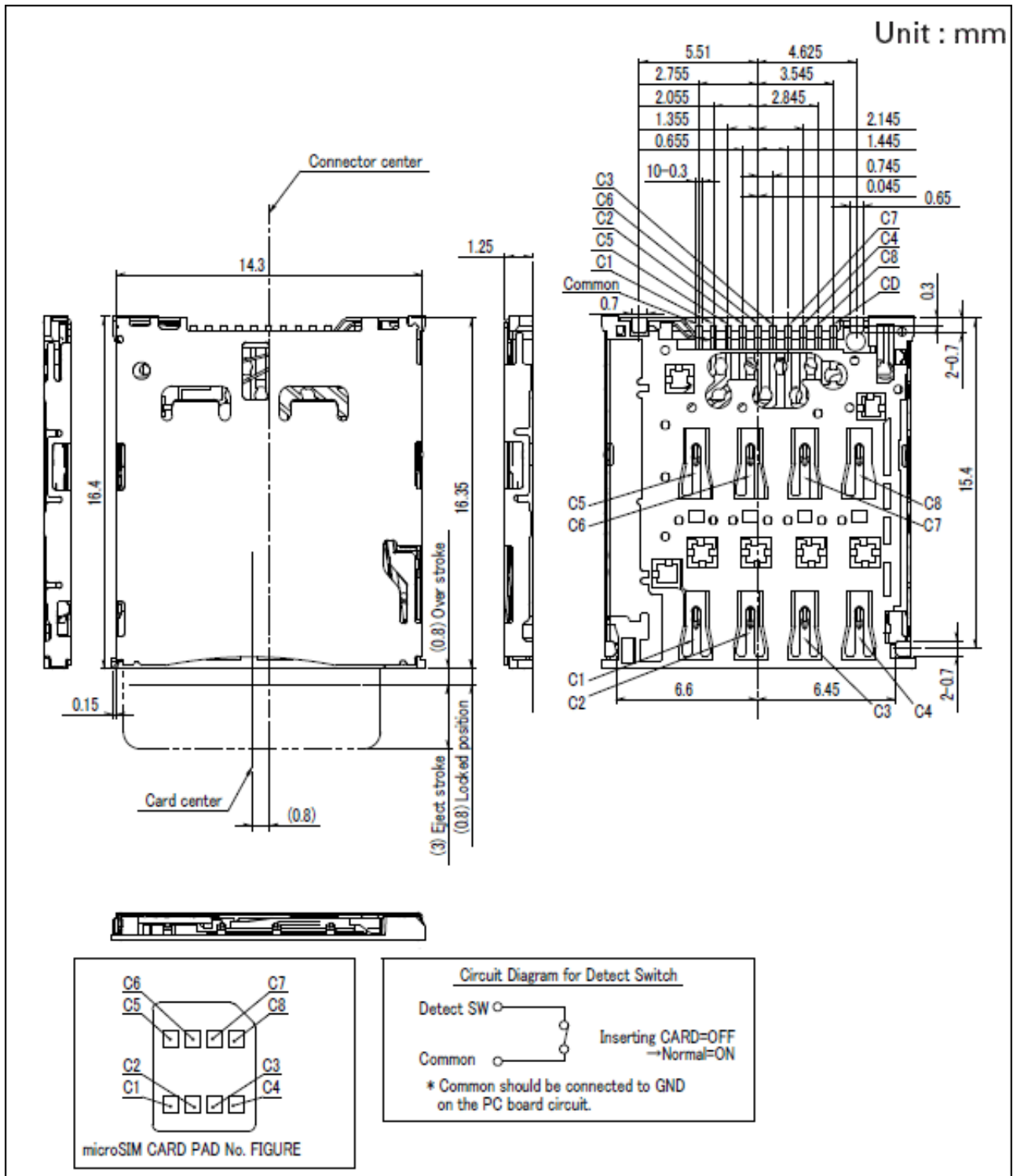
For microSIM Card (Push-push Type) SCGD Series

Part number	SCGD1B0208	
Applicable media	microSIM card	
Media ejection structure	Push-push type	
Mounting type	Surface mounting type	
Mounting style	Standard mount	
Card eject stroke	3mm	
Stand-off	0mm	
Minimum order unit (pcs.)	1,600	
Operating temperature range	-25°C to +60°C	
Voltage proof	250V AC 1 minute	
Insulation resistance (Initial)	1,000MΩ min.	
Contact resistance (Initial)	Connector contacts	100mΩ max.
	Detection Switch	500mΩ max.
Insertion and removal cycle	5,000 cycles	

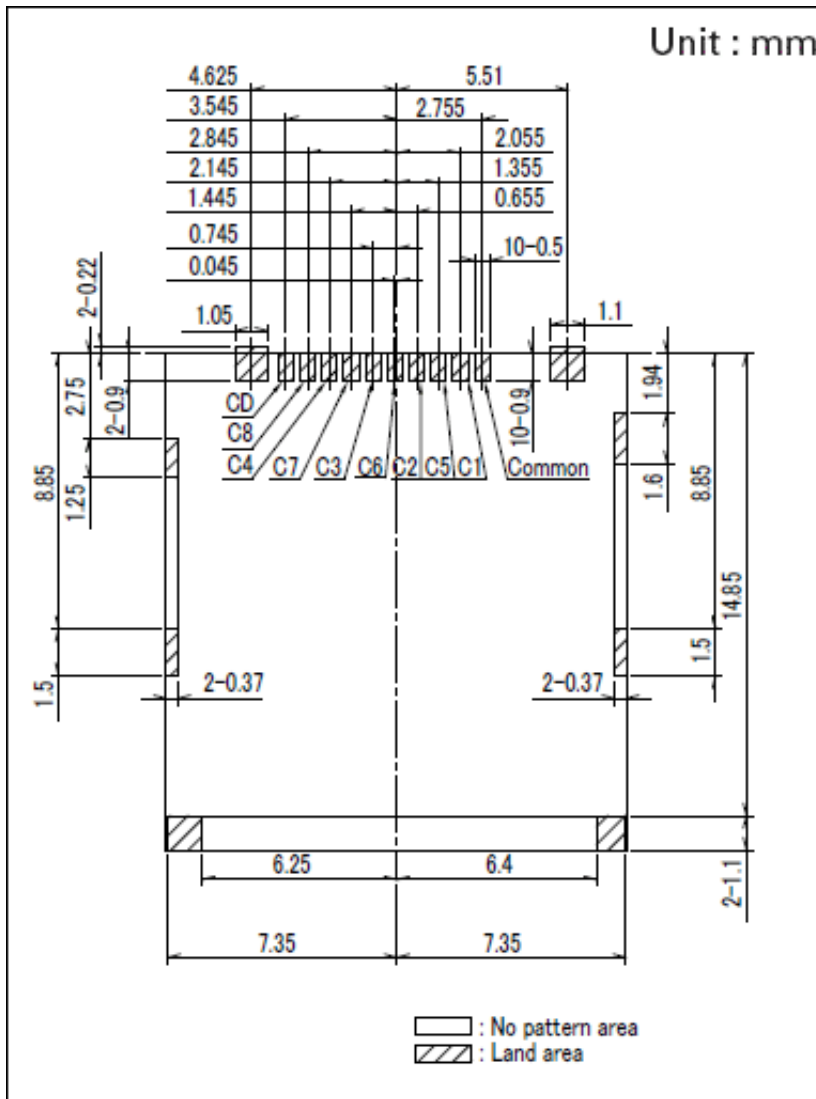
Photo



Dimensions

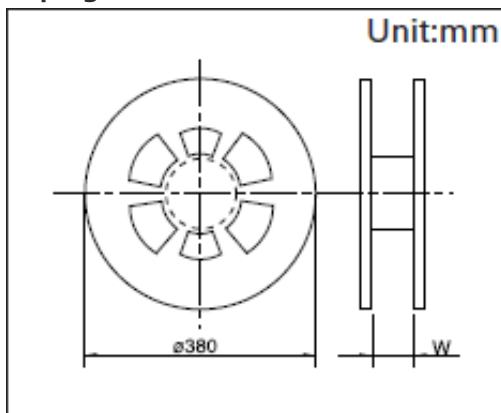


Mounting Dimensions



Packing Specifications

Taping



Number of packages 1 reel (pcs.)	1,600
1 case / Japan	4,800
1 case / export	9,600

packing

Reel width W(mm)	57.5
Tape width (mm)	56
Export package measurements (mm)	403×403×303

Soldering Conditions

Example of Reflow Soldering Condition (Reference)

1. Heating method

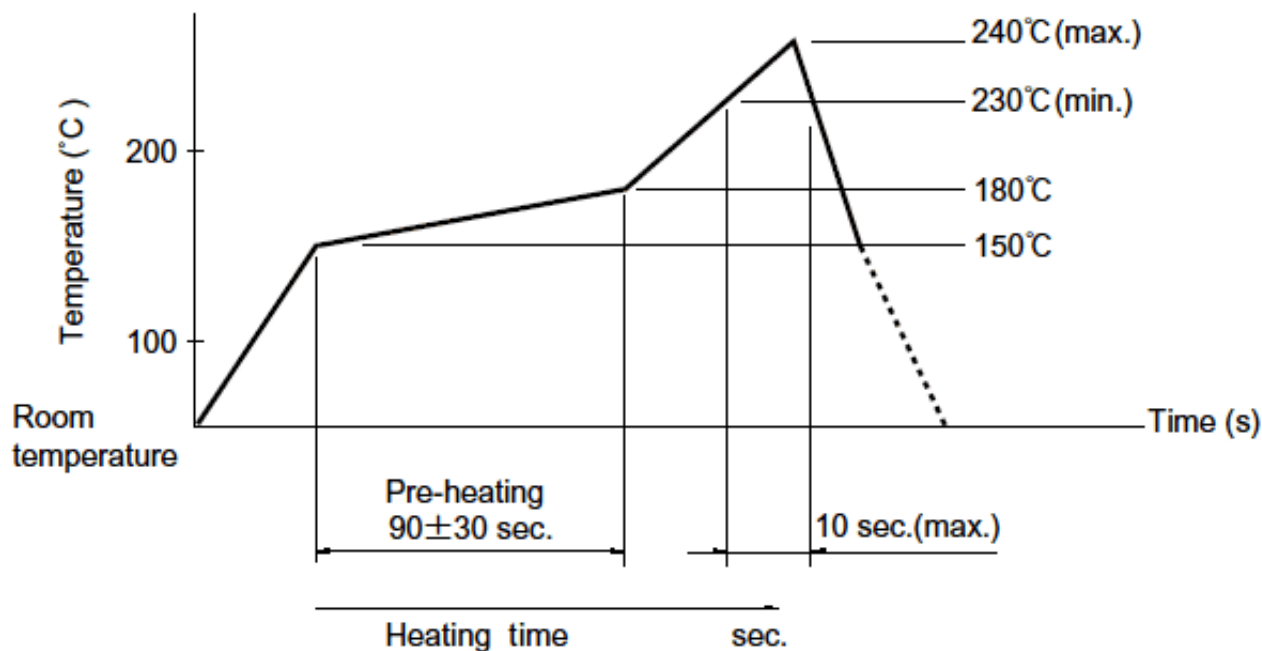
Double heating method with infrared heater.

2. Temperature measurement

Thermocouple 0.1 to 0.2 Φ CA (K) or CC (T) at soldering portion.

3. Temperature profile.

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Notes are common to this series/models.

1. This site catalog shows only outline specifications. When using the products, please obtain formal specifications for supply.
2. Please place purchase orders per minimum order unit (integer).